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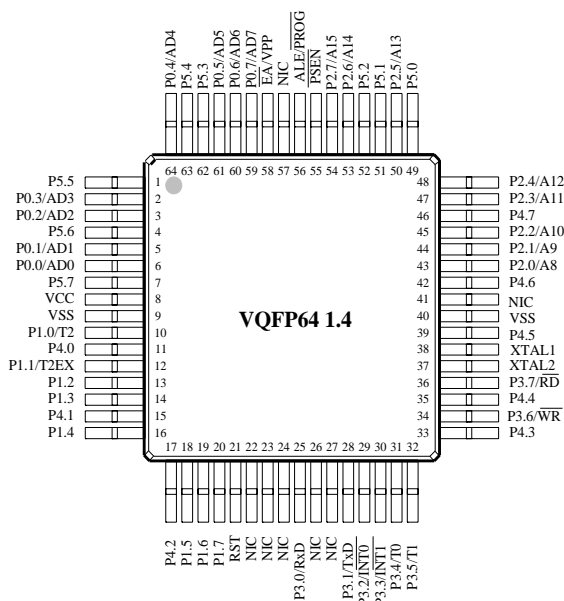
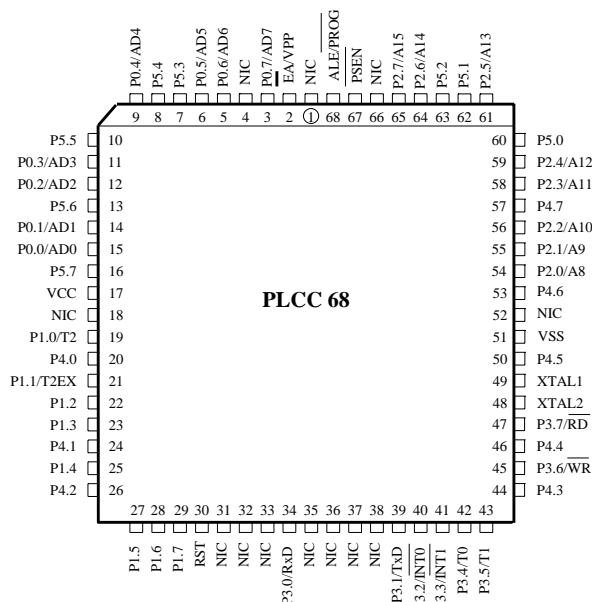
What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/30MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts80c51rd2-via



NIC: No Internal Connection

Reset	9	10	4	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC} . If the hardware watchdog reaches its time-out, the reset pin becomes an output during the time the internal reset is activated.
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6.2. Dual Data Pointer Register Ddptr

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 4.) that allows the program code to switch between them (Refer to Figure 3).

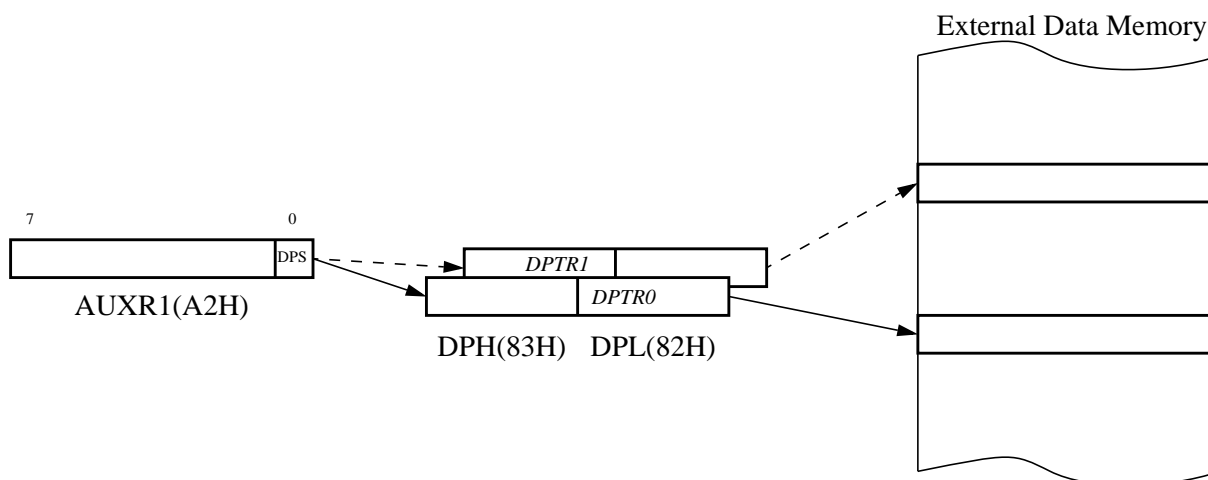


Figure 3. Use of Dual Pointer

Table 4. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	-	-	DPS
	Reset value	X	X	X	X	0	X	X	0

Symbol	Function
-	Not implemented, reserved for future use. ^a
DPS	Data Pointer Selection.
	DPS Operating Mode
	0 DPTR0 Selected
	1 DPTR1 Selected
GF3	This bit is a general purpose user flag ^b .

- a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.
- b. GF3 will not be available on first version of the RC devices.

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

6.3. Expanded RAM (XRAM)

The TS80C51Rx2 provide additional Bytes of random access memory (RAM) space for increased data parameter handling and high level language usage.

RA2, RB2 and RC2 devices have 256 bytes of expanded RAM, from 00H to FFH in external data space; RD2 devices have 768 bytes of expanded RAM, from 00H to 2FFH in external data space.

The TS80C51Rx2 has internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared in the AUXR register. (See Table 5.)

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. **For example: MOV 0A0H, # data** ,accesses the SFR at location 0A0H (which is P2).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM. **For example: MOV @R0, # data** where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).
- The 256 or 768 XRAM bytes can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 or 768 bytes of external data memory.
- With EXTRAM = 0, the XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. **An access to XRAM will not affect ports P0, P2, P3.6 (\overline{WR}) and P3.7 (\overline{RD}).** **For example, with EXTRAM = 0, MOVX @R0, # data** where R0 contains 0A0H, accesses the XRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) (higher than 2FFH (i.e. 0300H to FFFFH for RD devices) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address busses, and P3.6 and P3.7 as write and read timing signals. Refer to Figure . For RD devices, accesses to expanded RAM from 100H to 2FFH can only be done thanks to the use of DPTR.
- With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an eight-bit address multiplexed with data on Port0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a sixteen-bit address. Port2 outputs the high-order eight address bits (the contents of DPH) while Port0 multiplexes the low-order eight address bits (DPL) with data. MOVX @ Ri and MOVX @DPTR will generate either read or write signals on P3.6 (\overline{WR}) and P3.7 (\overline{RD}).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

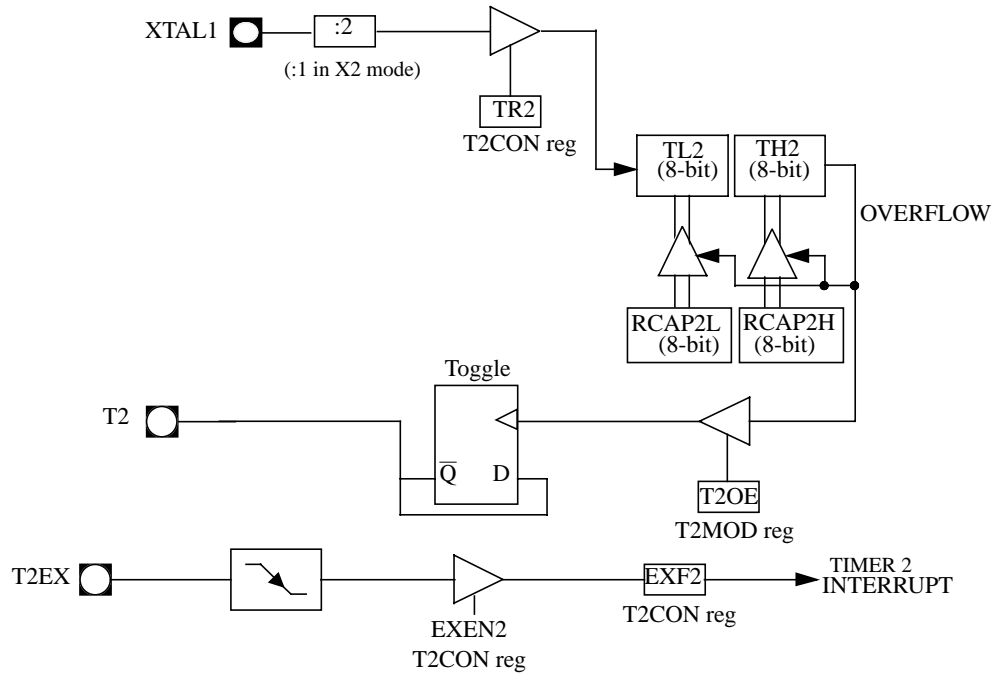


Figure 6. Clock-Out Mode $C/\overline{T2} = 0$

Table 7. T2MOD Register

T2MOD - Timer 2 Mode Control Register (C9h)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	T2OE	DCEN

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	T2OE	Timer 2 Output Enable bit Clear to program P1.0/T2 as clock input or I/O port. Set to program P1.0/T2 as clock output.
0	DCEN	Down Counter Enable bit Clear to disable timer 2 as up/down counter. Set to enable timer 2 as up/down counter.

Reset Value = XXXX XX00b

Not bit addressable

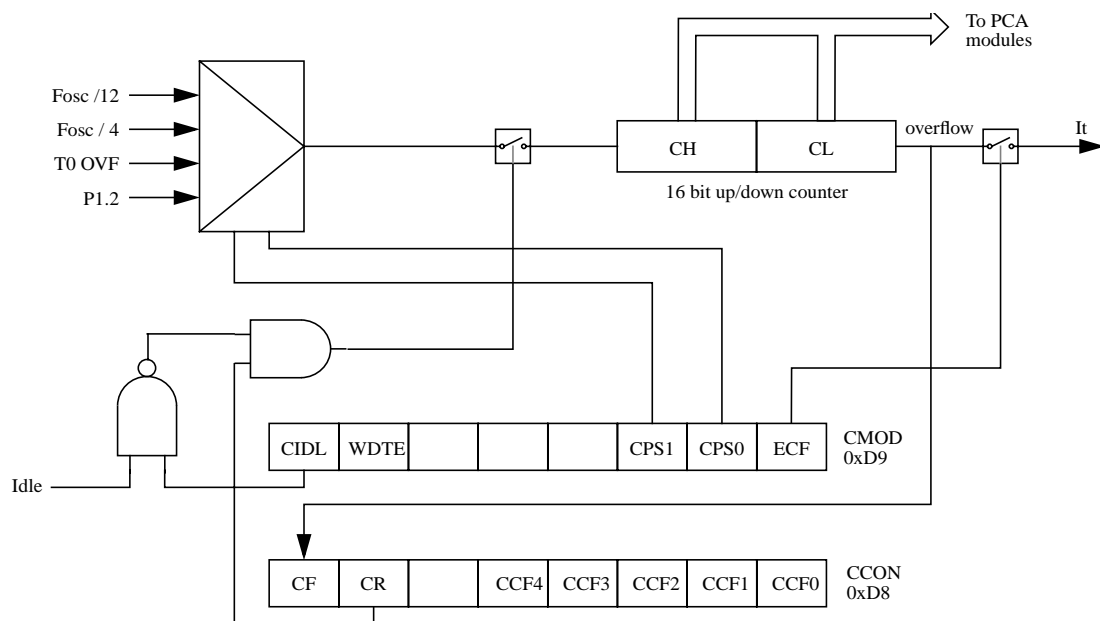


Figure 7. PCA Timer/Counter

Table 8. CMOD: PCA Counter Mode Register

CMOD Address 0D9H		CIDL	WDTE	-	-	-	CPS1	CPS0	ECF
Reset value		0	0	X	X	X	0	0	0

Symbol	Function		
CIDL	Counter Idle control: CIDL = 0 programs the PCA Counter to continue functioning during idle Mode. CIDL = 1 programs it to be gated off during idle.		
WDTE	Watchdog Timer Enable: WDTE = 0 disables Watchdog Timer function on PCA Module 4. WDTE = 1 enables it.		
-	Not implemented, reserved for future use. ^a		
CPS1	PCA Count Pulse Select bit 1.		
CPS0	PCA Count Pulse Select bit 0.		
	CPS1	CPS0	Selected PCA input. ^b
	0	0	Internal clock $f_{osc}/12$ (Or $f_{osc}/6$ in X2 Mode).
	0	1	Internal clock $f_{osc}/4$ (Or $f_{osc}/2$ in X2 Mode).
	1	0	Timer 0 Overflow
	1	1	External clock at ECI/P1.2 pin (max rate = $f_{osc}/8$)
ECF	PCA Enable Counter Overflow interrupt: ECF = 1 enables CF bit in CCON to generate an interrupt. ECF = 0 disables that function of CF.		

- a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.
- b. f_{osc} = oscillator frequency

The CMOD SFR includes three additional bits associated with the PCA (See Figure 7 and Table 8).

- The CIDL bit which allows the PCA to stop during idle mode.
- The WDTE bit which enables or disables the watchdog function on module 4.

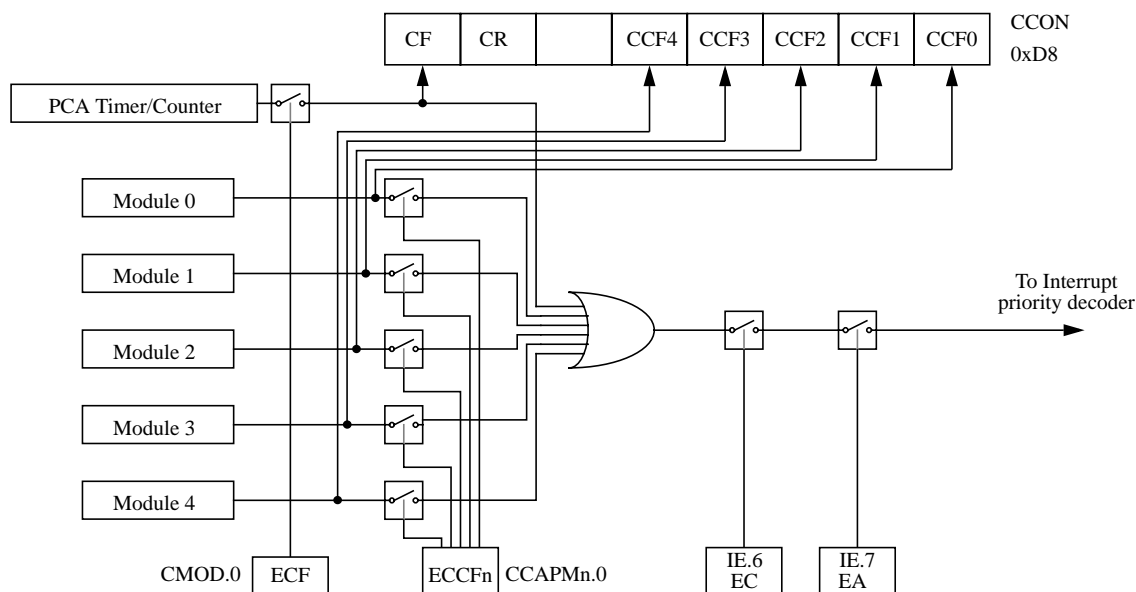


Figure 8. PCA Interrupt System

PCA Modules: each one of the five compare/capture modules has six possible functions. It can perform:

- 16-bit Capture, positive-edge triggered,
- 16-bit Capture, negative-edge triggered,
- 16-bit Capture, both positive and negative-edge triggered,
- 16-bit Software Timer,
- 16-bit High Speed Output,
- 8-bit Pulse Width Modulator.

In addition, module 4 can be used as a Watchdog Timer.

Each module in the PCA has a special function register associated with it. These registers are: CCAPM0 for module 0, CCAPM1 for module 1, etc. (See Table 10). The registers contain the bits that control the mode that each module will operate in.

- The ECCF bit (CCAPMn.0 where n=0, 1, 2, 3, or 4 depending on the module) enables the CCF flag in the CCON SFR to generate an interrupt when a match or compare occurs in the associated module.
- PWM (CCAPMn.1) enables the pulse width modulation mode.
- The TOG bit (CCAPMn.2) when set causes the CEX output associated with the module to toggle when there is a match between the PCA counter and the module's capture/compare register.
- The match bit MAT (CCAPMn.3) when set will cause the CCFn bit in the CCON register to be set when there is a match between the PCA counter and the module's capture/compare register.
- The next two bits CAPN (CCAPMn.4) and CAPP (CCAPMn.5) determine the edge that a capture input will be active on. The CAPN bit enables the negative edge, and the CAPP bit enables the positive edge. If both bits are set both edges will be enabled and a capture will occur for either transition.
- The last bit in the register ECOM (CCAPMn.6) when set enables the comparator function.

Table 11 shows the CCAPMn settings for the various PCA functions.

6.5.4. Pulse Width Modulator Mode

All of the PCA modules can be used as PWM outputs. Figure 12 shows the PWM function. The frequency of the output depends on the source for the PCA timer. All of the modules will have the same frequency of output because they all share the PCA timer. The duty cycle of each module is independently variable using the module's capture register CCAPLn. When the value of the PCA CL SFR is less than the value in the module's CCAPLn SFR the output will be low, when it is equal to or greater than the output will be high. When CL overflows from FF to 00, CCAPLn is reloaded with the value in CCAPHn. This allows updating the PWM without glitches. The PWM and ECOM bits in the module's CCAPMn register must be set to enable the PWM mode.

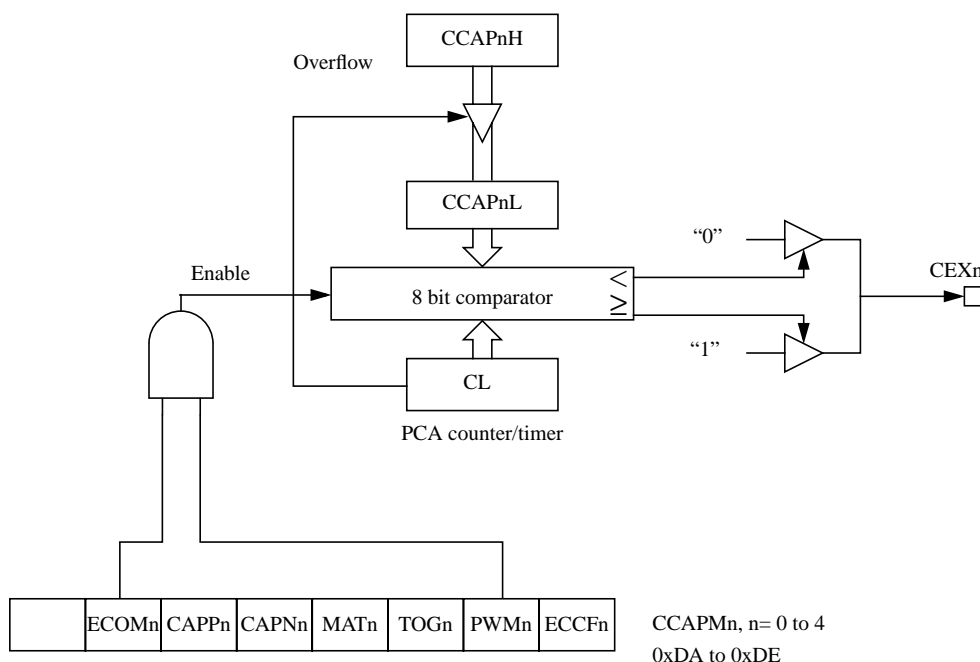


Figure 12. PCA PWM Mode

6.5.5. PCA Watchdog Timer

An on-board watchdog timer is available with the PCA to improve the reliability of the system without increasing chip count. Watchdog timers are useful for systems that are susceptible to noise, power glitches, or electrostatic discharge. Module 4 is the only PCA module that can be programmed as a watchdog. However, this module can still be used for other modes if the watchdog is not needed. Figure 10 shows a diagram of how the watchdog works. The user pre-loads a 16-bit value in the compare registers. Just like the other compare modes, this 16-bit value is compared to the PCA timer value. If a match is allowed to occur, an internal reset will be generated. This will not cause the RST pin to be driven high.

In order to hold off the reset, the user has three options:

- 1. periodically change the compare value so it will never match the PCA timer,
- 2. periodically change the PCA timer value so it will never match the compare values, or
- 3. disable the watchdog by clearing the WDTE bit before a match occurs and then re-enable it.

The first two options are more reliable because the watchdog timer is never disabled as in option #3. If the program counter ever goes astray, a match will eventually occur and cause an internal reset. The second option is also not recommended if other PCA modules are being used. Remember, the PCA timer is the time base for all modules; changing the time base for other modules would not be a good idea. Thus, in most applications the first solution is the best option.

This watchdog timer won't generate a reset out on the reset pin.

6.7. Interrupt System

The TS80C51Rx2 has a total of 7 interrupt vectors: two external interrupts ($\overline{\text{INT0}}$ and $\overline{\text{INT1}}$), three timer interrupts (timers 0, 1 and 2), the serial port interrupt and the PCA global interrupt. These interrupts are shown in Figure 16.

WARNING: Note that in the first version of RC devices, the PCA interrupt is in the lowest priority. Thus the order in $\overline{\text{INT0}}$, TF0, $\overline{\text{INT1}}$, TF1, RI or TI, TF2 or EXF2, PCA.

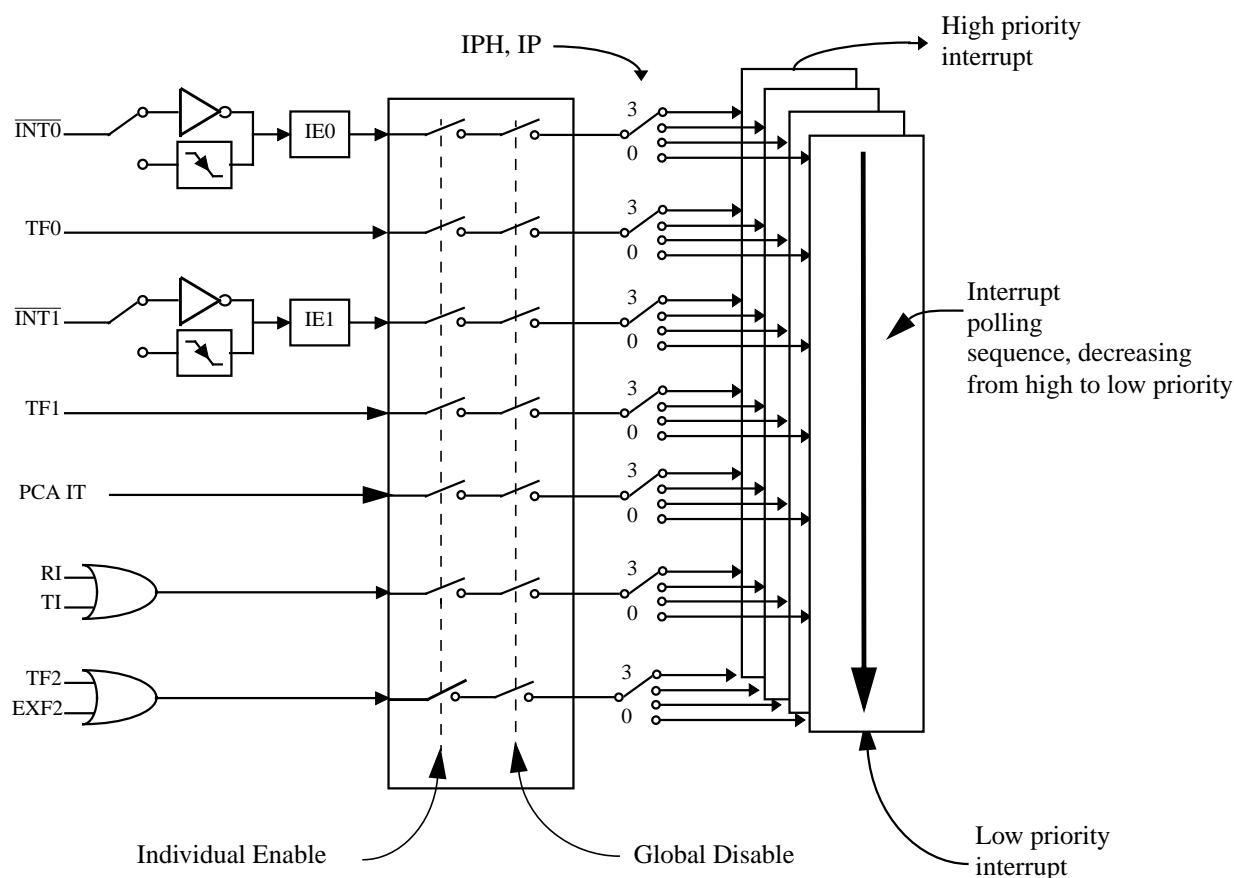


Figure 16. Interrupt Control System

Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 19.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 20.) and in the Interrupt Priority High register (See Table 21.). shows the bit values and priority levels associated with each combination.

The PCA interrupt vector is located at address 0033H. All other vector addresses are the same as standard C52 devices.

6.8. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirety : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occurred during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

6.9. Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 17., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{INT0}$ and $\overline{INT1}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.

Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 17. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.

Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C51Rx2 into power-down mode.

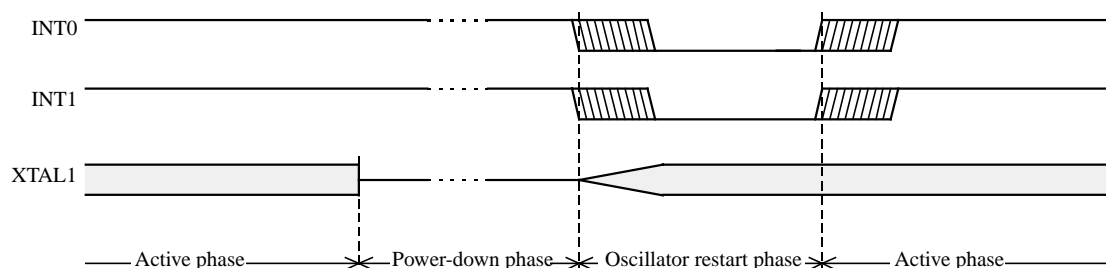


Figure 17. Power-Down Exit Waveform

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does not affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

NOTE: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

6.13. Reduced EMI Mode

The ALE signal is used to demultiplex address and data buses on port 0 when used with external program or data memory. Nevertheless, during internal code execution, ALE signal is still generated. In order to reduce EMI, ALE signal can be disabled by setting AO bit.

The AO bit is located in AUXR register at bit location 0. As soon as AO is set, ALE is no longer output but remains active during MOVX and MOVC instructions and external fetches. During ALE disabling, ALE pin is weakly pulled high.

Table 27. AUXR Register

AUXR - Auxiliary Register (8Eh)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	EXTRAM	AO

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	EXTRAM	EXTRAM bit See Table 5.
0	AO	ALE Output bit Clear to restore ALE operation during internal fetches. Set to disable ALE operation during internal fetches.

Reset Value = XXXX XX00b

Not bit addressable

10. Electrical Characteristics

10.1. Absolute Maximum Ratings ⁽¹⁾

Ambiant Temperature Under Bias:

C = commercial

0°C to 70°C

I = industrial

-40°C to 85°C

Storage Temperature

-65°C to + 150°C

Voltage on V_{CC} to V_{SS}

-0.5 V to + 7 V

Voltage on V_{PP} to V_{SS}

-0.5 V to + 13 V

Voltage on Any Pin to V_{SS}

-0.5 V to $V_{CC} + 0.5$ V

Power Dissipation

1 W⁽²⁾

NOTES

1. Stresses at or above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

10.2. Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating I_{cc} measurements under reset, which made sense for the designs where the CPU was running under reset. In Atmel Wireless & Microcontrollers new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel Wireless & Microcontrollers presents a new way to measure the operating I_{cc} :

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = V_{CC} , RST = V_{SS} , XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating I_{cc} .

TS80C51RA2/RD2

TS83C51RB2/RC2/RD2

TS87C51RB2/RC2/RD2



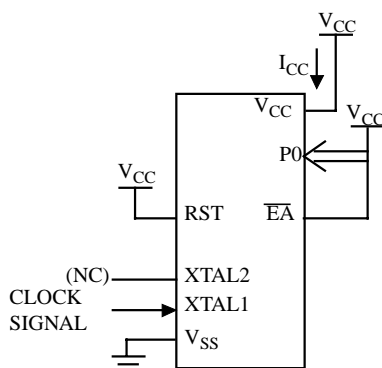
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC} idle	Power Supply Current Maximum values, X1 mode: ⁽⁷⁾			0.15 Freq (MHz) + 0.2 @ 12MHz 2 @ 16MHz 2.6	mA	$V_{CC} = 3.3 \text{ V}^{(2)}$

NOTES

- I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5 \text{ ns}$ (see Figure 24.), $V_{IL} = V_{SS} + 0.5 \text{ V}$, $V_{IH} = V_{CC} - 0.5 \text{ V}$; XTAL2 N.C.; $\overline{EA} = RST = \text{Port } 0 = V_{CC}$. I_{CC} would be slightly higher if a crystal oscillator is used.
- Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5 \text{ ns}$, $V_{IL} = V_{SS} + 0.5 \text{ V}$, $V_{IH} = V_{CC} - 0.5 \text{ V}$; XTAL2 N.C.; Port 0 = V_{CC} ; $\overline{EA} = RST = V_{SS}$ (see Figure 22.).
- Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA} = V_{SS}$; PORT 0 = V_{CC} ; XTAL2 N.C.; RST = V_{SS} (see Figure 23.).
- Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.
- Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
- Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
Maximum I_{OL} per port pin: 10 mA
Maximum I_{OL} per 8-bit port:
Port 0: 26 mA
Ports 1, 2, 3 and 4 and 5 when available: 15 mA
Maximum total I_{OL} for all output pins: 71 mA

If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.

- For other values, please contact your sales office.
- Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH} , $T_{CHCL} = 5 \text{ ns}$ (see Figure 24.), $V_{IL} = V_{SS} + 0.5 \text{ V}$, $V_{IH} = V_{CC} - 0.5 \text{ V}$; XTAL2 N.C.; $\overline{EA} = \text{Port } 0 = V_{CC}$; RST = V_{SS} . The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.



All other pins are disconnected.

Figure 20. I_{CC} Test Condition, under reset

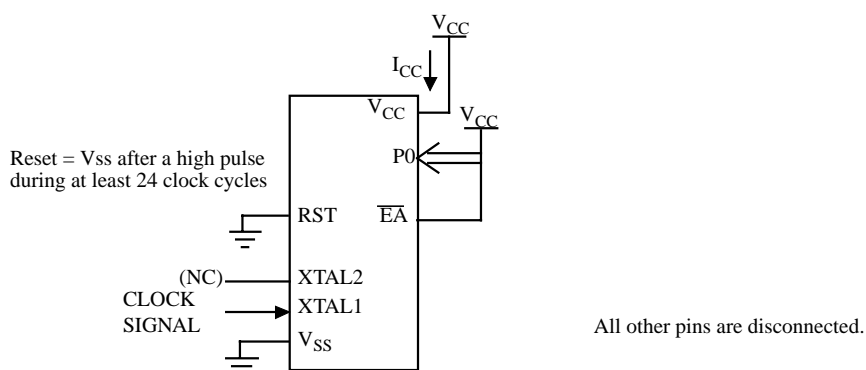


Figure 21. Operating I_{CC} Test Condition

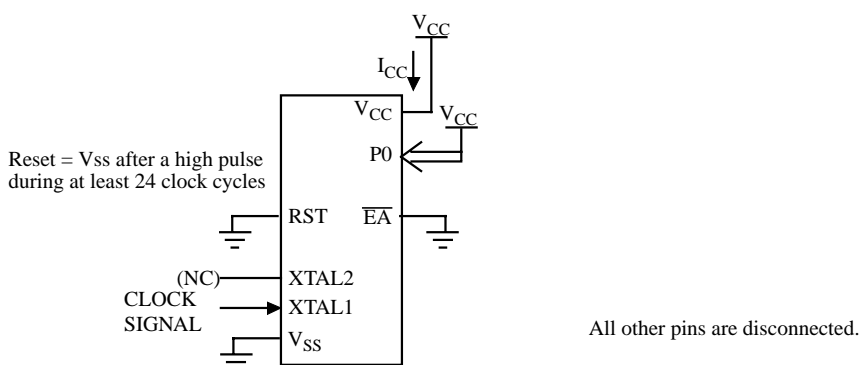


Figure 22. I_{CC} Test Condition, Idle Mode

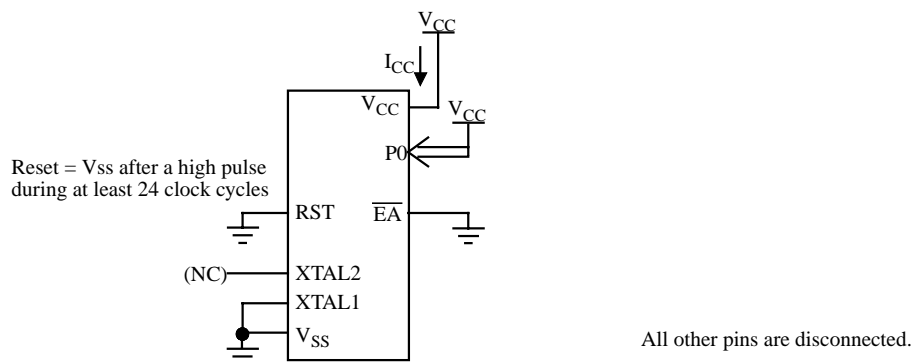


Figure 23. I_{CC} Test Condition, Power-Down Mode

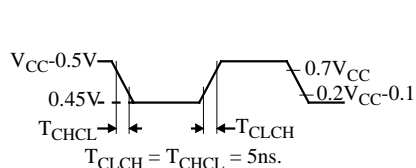


Figure 24. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes

10.5.4. External Data Memory Characteristics

Table 39. Symbol Description

Symbol	Parameter
T_{RLRH}	\overline{RD} Pulse Width
T_{WLWH}	\overline{WR} Pulse Width
T_{RLDV}	\overline{RD} to Valid Data In
T_{RHDX}	Data Hold After \overline{RD}
T_{RHDZ}	Data Float After \overline{RD}
T_{LLDV}	ALE to Valid Data In
T_{AVDV}	Address to Valid Data In
T_{LLWL}	ALE to \overline{WR} or \overline{RD}
T_{AVWL}	Address to \overline{WR} or \overline{RD}
T_{QVWX}	Data Valid to \overline{WR} Transition
T_{QVWH}	Data set-up to \overline{WR} High
T_{WHQX}	Data Hold After \overline{WR}
T_{RLAZ}	\overline{RD} Low to Address Float
T_{WHLH}	\overline{RD} or \overline{WR} High to ALE high

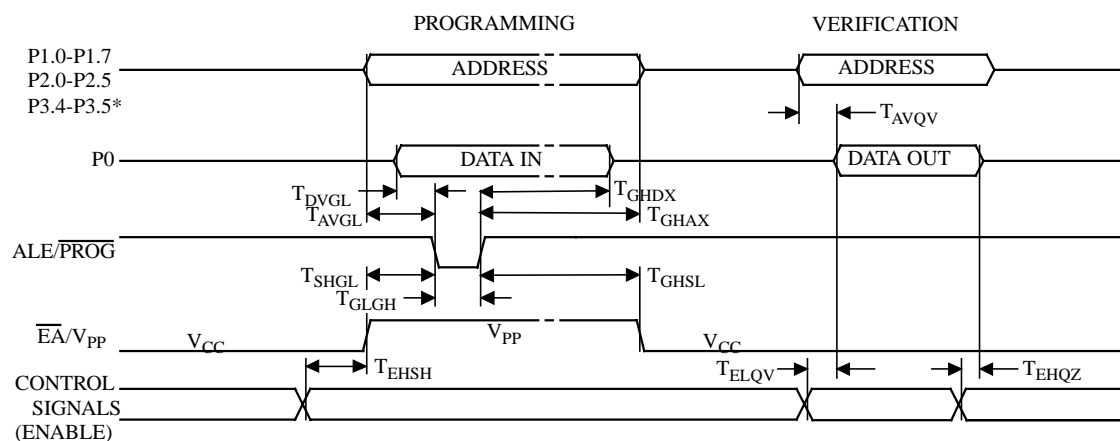
10.5.9. EPROM Programming and Verification Characteristics

$T_A = 21^\circ\text{C}$ to 27°C ; $V_{SS} = 0\text{V}$; $V_{CC} = 5\text{V} \pm 10\%$ while programming. V_{CC} = operating range while verifying

Table 45. EPROM Programming Parameters

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Supply Voltage	12.5	13	V
I_{PP}	Programming Supply Current		75	mA
$1/T_{CLCL}$	Oscillator Frequency	4	6	MHz
T_{AVGL}	Address Setup to $\overline{\text{PROG}}$ Low	$48 T_{CLCL}$		
T_{GHAX}	Adress Hold after $\overline{\text{PROG}}$	$48 T_{CLCL}$		
T_{DVGL}	Data Setup to $\overline{\text{PROG}}$ Low	$48 T_{CLCL}$		
T_{GHDX}	Data Hold after $\overline{\text{PROG}}$	$48 T_{CLCL}$		
T_{EHS}	(Enable) High to V_{PP}	$48 T_{CLCL}$		
T_{SHGL}	V_{PP} Setup to $\overline{\text{PROG}}$ Low	10		μs
T_{GHSL}	V_{PP} Hold after $\overline{\text{PROG}}$	10		μs
T_{GLGH}	$\overline{\text{PROG}}$ Width	90	110	μs
T_{AVQV}	Address to Valid Data		$48 T_{CLCL}$	
T_{ELQV}	ENABLE Low to Data Valid		$48 T_{CLCL}$	
T_{EHQZ}	Data Float after ENABLE	0	$48 T_{CLCL}$	

10.5.10. EPROM Programming and Verification Waveforms



* 8KB: up to P2.4, 16KB: up to P2.5, 32KB: up to P3.4, 64KB: up to P3.5

Figure 29. EPROM Programming and Verification Waveforms

10.5.11. External Clock Drive Characteristics (XTAL1)

Table 46. AC Parameters

Symbol	Parameter	Min	Max	Units
T_{CLCL}	Oscillator Period	25		ns
T_{CHCX}	High Time	5		ns
T_{CLCX}	Low Time	5		ns
T_{CLCH}	Rise Time		5	ns
T_{CHCL}	Fall Time		5	ns
T_{CHCX}/T_{CLCX}	Cyclic ratio in X2 mode	40	60	%

10.5.12. External Clock Drive Waveforms

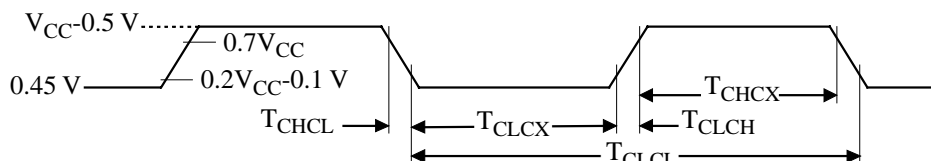


Figure 30. External Clock Drive Waveforms

10.5.13. AC Testing Input/Output Waveforms

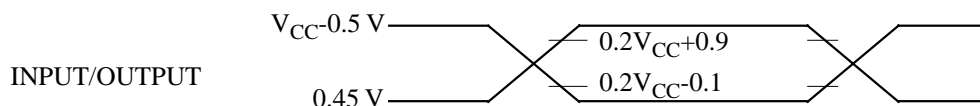


Figure 31. AC Testing Input/Output Waveforms

AC inputs during testing are driven at $V_{CC} - 0.5$ for a logic “1” and 0.45V for a logic “0”. Timing measurement are made at V_{IH} min for a logic “1” and V_{IL} max for a logic “0”.

10.5.14. Float Waveforms

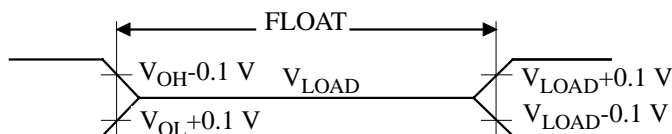


Figure 32. Float Waveforms

11. Ordering Information

TS	87C51RD2	-M	C	B	R
	-M: VCC: 5V +/- 10% 40 MHz, X1 mode 20 MHz, X2 mode -V: VCC: 5V +/- 10% 40 MHz, X1 mode 30 MHz, X2 mode -L: VCC: 2.7 to 5.5 V 30 MHz, X1 mode 20 MHz, X2 mode -E: Samples		Packages: A: PDIL 40 B: PLCC 44 E: VQFP 44 (1.4mm) J: Window CDIL 40* K: Window CQPJ 44* L: PLCC68 (RD devices only)* M: VQFP64, square package, 1.4mm (RD devices only)* N: JLCC68 (RD devices only)*		Conditioning R: Tape & Reel D: Dry Pack B: Tape & Reel and Dry Pack
Part Number 80C51RA2 (ROMless, 256 bytes XRAM) 80C51RD2 (ROMless, 768bytes XRAM) 83C51RB2zzz (16k ROM, zzz is the customer code) 83C51RC2zzz (32k ROM, zzz is the customer code) 83C51RD2zzz (64k ROM, zzz is the customer code) 87C51RB2 (16k OTP EPROM) 87C51RC2 (32k OTP EPROM) 87C51RD2 (64k OTP EPROM)					
Temperature Range C: Commercial 0 to 70°C I: Industrial -40 to 85°C					

(*) Check with Atmel Wireless & Microcontrollers Sales Office for availability. Ceramic packages (J, K, N) are available for prototyping, not for volume production. Ceramic packages are available for OTP only.

Table 47. Maximum Clock Frequency

Code	-M	-V	-L	Unit
Standard Mode, oscillator frequency	40	40	30	MHz
Standard Mode, internal frequency	40	40	30	
X2 Mode, oscillator frequency	20	30	20	MHz
X2 Mode, internal equivalent frequency	40	60	40	

Table 48. Possible Ordering Entries

	TS80C51RA2/RD2 ROMless	TS83C51RB2/RC2/RD2 ^{zzz} ROM	TS87C51RB2/RC2/RD2 OTP
-MCA	X	X	X
-MCB	X	X	X
-MCE	X	X	X
-MCL	RD2 only	RD2 only	RD2 only
-MCM	RD2 only	RD2 only	RD2 only
-VCA	X	X	X
-VCB	X	X	X
-VCE	X	X	X
-VCL	RD2 only	RD2 only	RD2 only
-VCM	RD2 only	RD2 only	RD2 only
-LCA	X	X	X
-LCB	X	X	X
-LCE	X	X	X
-LCL	RD2 only	RD2 only	RD2 only
-LCM	RD2 only	RD2 only	RD2 only
-MIA	X	X	X
-MIB	X	X	X
-MIE	X	X	X
-MIL	RD2 only	RD2 only	RD2 only
-MIM	RD2 only	RD2 only	RD2 only
-VIA	X	X	X
-VIB	X	X	X
-VIE	X	X	X
-VIL	RD2 only	RD2 only	RD2 only
-VIM	RD2 only	RD2 only	RD2 only
-LIA	X	X	X
-LIB	X	X	X
-LIE	X	X	X
-LIL	RD2 only	RD2 only	RD2 only
-LIM	RD2 only	RD2 only	RD2 only
-EA	X		X
-EB	X		X
-EE	X		X
-EL	RD2 only		RD2 only
-EM	RD2 only		RD2 only
-EJ			RC2 and RD2 only
-EK			RC2 and RD2 only
-EN			RD2 only

- -Ex for samples
- Tape and Reel available for B, E, L and M packages
- Dry pack mandatory for E and M packages